

## CORRIGENDUM 1

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### 2 Normative references

*Delete:*

IEC 61190-1-1, *Attachment materials for electronic assemblies – Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly*

IEC 61190-1-2, *Attachment materials for electronic assemblies – Part 1-2: Requirements for solder pastes for high-quality interconnections in electronics assembly*

IEC 61190-1-3, *Attachment materials for electronic assemblies – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications*

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#### A.2.4.4 Post-treatment (flux removal)

*First sentence*

*Instead of:*

*“(propanol)”*

*read:*

*“(isopropanol)”.*

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#### A.3.4.1 Soldering process, a) Pre-treatment

*Instead of:*

*“as specified in Figure 3”*

*read:*

*“as specified in Figure 2”.*